

TEXT Strategy

application # 101902188

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	36204	((solder) adj (ball\$1 or bump\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/22 11:20
L2	21817	((gold or Au or copper or cu or tin) adj (coat\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/22 11:09
L3	636	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/22 11:09
L4	40	(solder adj ball\$1) with ( cu or copper) with (coat or coating)	USPAT	OR	OFF	2005/08/22 11:24
S1	102	("5718047" "4845405" "5434749" "5552967" "5560795" "5831441" "5854558" "4257202" "4931599" "6074552" "6223429" "6223429" "3864821" "4587502" "4595897" "4839713" "4957576" "5006079" "5187496" "5193796" "5352126" "5361488" "5419722" "5477993" "5508561" "5578392" "5584414" "5628919" "5631613" "5633204" "5634825" "5640051" "5654869" "5666270" "5707407" "5744859" "5753901" "5760945" "5763037" "5792520" "5877553" "5925961" "5962958" "5983055" "6015523" "6036901" "6038004" "6081310" "6114750" "6127622").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 17:14
S2	919	conductive adj projection\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 17:16
S3	5064	junction adj structure\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 13:48

S4	189087	insulating adj layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/20 13:44
S5	1950109	resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 17:17
S6	45878	(ring adj form) or (fillet)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 17:18
S7	1	S2 and S3 and S4 and S5 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 17:19
S8	1	S3 and S4 and S5 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 17:19
S9	83	S3 and S4 and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 17:30
S10	2296674	(bump\$1) or (solder adj ball\$1) or (terminal\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/20 13:35
S11	1632	S5 and S6 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/19 17:32

S12	1631	S11 not (S9 or S1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/20 13:34
S13	2297537	(bump\$1) or (solder adj ball\$1) or (terminal\$1) or (conductive adj projection\$1) or (conductive adj pillar\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 13:37
S14	668731	(insulating or resin) near3 (layer or film)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/20 13:47
S15	1114002	(insulating or resin) near3 (layer or film or material)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/20 13:46
S16	189855	S13 and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/20 13:47
S17	765793	(junction or inter\$1connection)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 13:49
S18	36611	S16 and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 13:49
S19	3433398	(trace\$1 or land\$1 or pad\$1 or conductor\$1 or pattern\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 13:53

S20	28292	S18 and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 13:53
S21	1637	S20 and thermosetting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 14:35
S22	638	(174/267).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/20 14:35
S23	629	S22 not S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 15:06
S24	2149	(174/260).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/20 15:05
S25	1926	S24 not (S22 or S21)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 16:11
S26	2105	(174/261).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/20 16:11
S27	1441	S26 not (S24 or S22 or S21)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 11:06

S28	4059	((174/267) or (174/260) or (174/261)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 11:07
S29	1798	(361/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 11:07
S30	1269	S29 not S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 11:24
S31	2539	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 11:25
S32	2315	S31 not (S29 or S28)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 11:25
S33	1959	(257/778).CCLS.	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 11:25
S34	1763	S33 not (S29 or S28)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 13:12
S35	0	(174/737).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 13:12

S36	1981	(257/737).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 13:12
S37	1367	S36 not (S33 or S29 or S28)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 13:39
S38	1708	(257/738).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 13:39
S39	708	S38 not (S36 or S33 or S29 or S28)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 13:50
S40	2	("6812124").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 15:52
S41	2	("6897761").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 15:58